Product End-of-Life Disassembly Instructions

Product Category: Networking Equipment
Marketing Name / Model [List multiple models if applicable.]
HP 5500-48G-PoE+-4SFP HI Switch w/2 Slt(JG542A)
HP 5500-48G-PoE+-4SFP HI TAA Swch w/2Slt(JG680A)

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.
1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

Item Description	Notes	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 sq cm	4
Batteries	All types including standard alkaline and lithium coin or button style batteries	0
Mercury-containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries	0
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm	Includes background illuminated displays with gas discharge lamps	0
Cathode Ray Tubes (CRT)		0
Capacitors / condensers (Containing PCB/PCT)		0
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height		0
External electrical cables and cords		0
Gas Discharge Lamps		0
Plastics containing Brominated Flame Retardants weighing > 25 grams (not including PCBs or PCAs already listed as a separate item above)		5
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner	Include the cartridges, print heads, tubes, vent chambers, and service stations.	0
Components and waste containing asbestos		0
Components, parts and materials containing refractory ceramic fibers		0
Components, parts and materials containing radioactive substances		0

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description	Tool Size (if applicable)
Screw driver	2#

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Unscrew the screws on mounting angle 2, and then remove mounting angle 2.
2. Unscrew the screws on mounting angle 3, and then remove mounting angle 3.
3. Unscrew the screws 1, and then remove the screws 1.
4. Unscrew the screws on the dummy bar 4,and then remove the dummy bar 4.
5. Remove the power 5 and the filler panel 6.
6. Unscrew the screws on top cover 7, and then remove top cover 7.
7. Remove plastic panel 8.
8. Remove all of the inner cables.
9. Unscrew the screws on fan-assembly 9, and then remove fan-assembly 9 from the chassis.
10. Unscrew the screws on the shutter 10, and then remove the shutter 10.
11. Unscrew the screws on PCB 11, and then remove PCB 11.
12. Unscrew the screws on fixing bracket 12, and then remove fixing bracket 12 from the chassis.
13. Unscrew the screws on PCB 13, and remove PCB 13 from the chassis.
14. Unscrew the screws 9-1,and then remove the fan 9-3 from the bracket 9-2.
15. Remove the lamp guide 13-2 from PCB 13-3.
16. Unscrew the screws on PCB 13-3, and then remove PCB 13-3 from PCB 13-1.
17. Unscrew the screws 13-5, and then remove all the hexagon posts 13-4.
18. Remove all of the labels from the chassis.

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

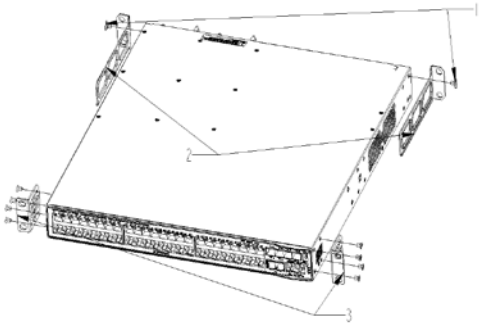

Figure 1 Remove mounting angle

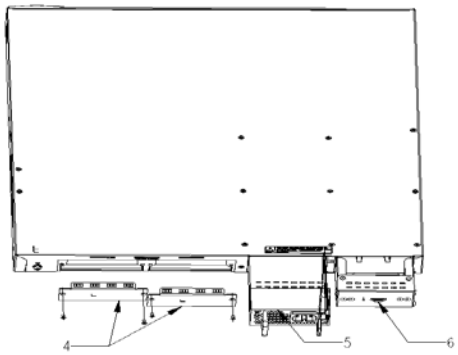

Figure 2 Rear of product

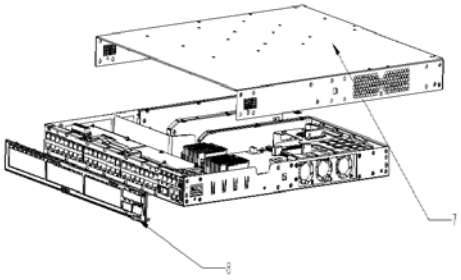

Figure 3 Treatments to the product

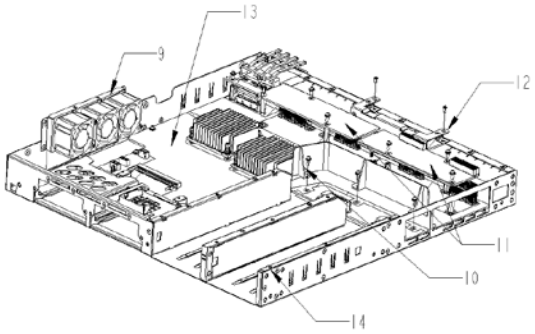

Figure 4 Treatments to the product

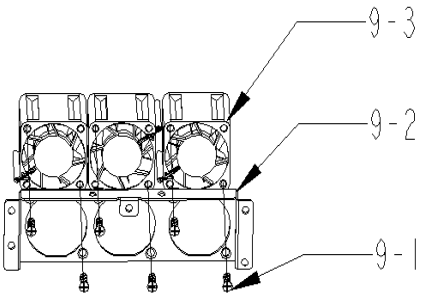

Figure 5 Treatments to fan-assembly

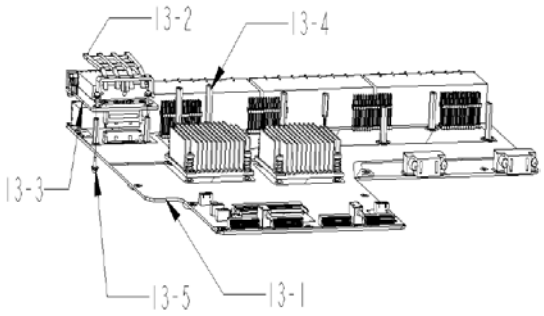

Figure 6 Treatments to PCB

3.3 Material of the facility built

Facility	Components	Material	Weight(g)	Weight percentage	Selective treatment for materials and components	Details
2		Fe	90	1.27%		Fe recycling
3		Fe	70	0.99%		Fe recycling
4		Fe	40*2	1.13%		Fe

						recycling
5			960	13.58%		Fe recycling
6		Fe	100	1.42%		Fe recycling
7		Fe	1730	24.48%		Fe recycling
8		PC+ABS	20	0.28%	Containing brominated flame retardants	Pla recycling
9						
	9-2	Fe	40	0.56%		Fe recycling
	9-3	PBT+Cu	90	1.27%	Containing brominated flame retardants	Cu recycling
10		PC+ABS	50	0.71%	Containing brominated flame retardants	Pla recycling
11		Complex PWB	80*2	2.26%	The surface of PCB is greater than 10 square centimeters;	
12		Fe	47	0.67%		Fe recycling
13						
	13-1	Complex PWB	1460	20.66%	The surface of PCB is greater than 10 square centimeters;	
	13-2	PC+ABS	10	0.14%	Containing brominated flame retardants	Pla recycling
	13-3	Complex PWB	50	0.71%	The surface of PCB is greater than 10 square centimeters;	
14		Fe	2110	29.86%		Fe recycling

4. Revised record

Date	Version	Author	Modify content
2013.01.08	V0	Li Meng	Initial version
2013.04.10	V1	Liu Baoquan	Add the module JG680A